



IEEE EMC Society
Technical Committee 4 – EMI Control
<http://www.emcs.org/committees/tc04/index.html>

Meeting Minutes

Place: Colorado Convention Center, Denver, CO, USA

Date: 06 August 2013

1 Welcome & Introductions

The meeting called to order at 1100 by Phil Berger, TC 4 Chair. Attendees introduced themselves.

2 Sign In Sheet

The attendance sheet was passed around for signature.

3 Review of Draft Agenda

The draft agenda was reviewed and approved.

4 Announcements

None

5 Last Meeting's Minutes

Minutes from the 2012 meeting in Pittsburgh, PA, USA were reviewed and accepted without changes.

6 Secretary's Report

Mr. Carlton, TC4 Secretary, reviewed the status of the Committee membership. At the 2012 meeting, the Committee had 27 attendees. A total of 25 attended the 2013 meeting.

The TC4 website has been updated with the latest information and made consistent with the sites of other TCs. In addition, TC4 has created a LinkedIn group to facilitate communications and coordination. The LinkedIn group currently has 37 members.

7 Action Items

None



8 Old Business

None

9 New Business

9.1 TC Officer Elections

The TC elects officers every two (2) years. The current officers have served one (1) year of their two year term. New officer elections will be held in 2014. The current officers are:

Chairman: Phil Berger

Vice-Chairman: John Kraemer

Secretary: Ross Carlton

9.2 TAC Performance Guidelines for TCs

Mr. Berger reviewed the new performance guidelines for EMCS TCs.

9.3 2013 Symposium Activities

Mr. Berger reviewed the TC's activities in support of the 2013 IEEE EMC Symposium. The TC supported the Symposium in the following ways:

- Chaired three Technical Sessions.
- Sponsored one half-day Workshop on "Grounding – Concepts, Physics and Myths".
- Sponsored a joint meeting with TechAmerica's G-46 EMC Committee and presented the half-day "EMI Control Update" – a series of eight presentations on various EMI control topics.
- Reviewed 23 technical papers.

9.4 Program of Work Discussion

Mr. Berger solicited the attendees for proposals on future work by the TC. After some discussion, the TC decided to form a new subcommittee (SC4) to focus on assessing the state of current EMI gasket test methods and to revise existing methods where possible and to create new methods where needed. SC4 was formed with the following initial officers:

Chairman: Gary Fenical

Vice-Chairman: Davy Pissoort

Secretary: Chris Brull

After review of the initial notes from the August meeting and past TC4 and TAC meeting minutes by the TC4 leadership, it was realized that TC4 already has a subcommittee to address EMI Gaskets - SC2, and the chairman is Gary Fenical. We will thus include Davy Pissoort as Vice-chair, and Chris Brull as secretary of SC2.



ACTION: Mr. Fenical will contact the Chair of TC2:EMC Measurements (Don Heirman) to coordinate efforts to review and revise standards regarding the characterization of EMI gaskets. (from TAC meeting)

9.5 Subcommittees

Mr. Berger requested that the TC4 subcommittees report their status.

- SC1: Grounding & bonding - William Bush
 - No update
- SC2: Gaskets – Gary Fenical
 - Subcommittee is still in its initial formation stage.
- SC3: Materials – Mark Montrose
 - No update

9.6 EMC Symposium 2014 plans

9.6.1 TC-4 Meeting

TC-4 will hold its next meeting at the 2013 EMC Symposium.

9.6.2 Workshops & Tutorials

The TC proposes to sponsor three ½-day workshops or tutorials. The general topic and the session organizer are as follows:

- EMI Control Issues in Equipments and Systems – Ms. Burnham
- Properties of Materials for EMI Control – Mr. Montrose
- EMI Gasket Evaluation Methods – Mr. Kunkel

ACTION: Mr. Montrose should contact TC11:Nanotechnology & Advanced Materials to investigate a joint Workshop or drawing authors from their membership. (from TAC meeting)

9.6.3 Special Sessions

The TC does not have any plans to propose a special session at this time.

9.6.4 Technical Paper Reviews

The TC will review technical papers for inclusion in the 2014 Symposium. At least three reviews are required for each submitted paper. The TC leadership will identify reviewers, make review assignments, and collect all comments.

10 Closing

The meeting was adjourned at 1150.

Minutes submitted by: Ross Carlton, Secretary, TC4 (ross.carlton@ieee.org)



TC4 Member List

NAME	AFFILITATION	EMAIL	SC	ATTEND
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Subcommittees

- 1: Grounding & Bonding
- 2: Gaskets
- 3: Materials